IN THE CLAIMS:

1. (Currently Amended) A dicing/die bonding sheet adhesively bonded to a semiconductor wafer prior to the dicing of said semiconductor wafer, wherein said dicing/die bonding sheet is provided with a base film, an undercoat layer formed on ~~the above-mentioned~~ said base film, and a silicone based adhesive agent layer formed on ~~the above-mentioned~~ said undercoat layer and having an adhesive surface adhesively bonded to ~~the above-mentioned~~ said semiconductor wafer.

2. (Currently Amended) The dicing/die bonding sheet according to claim 1, wherein ~~the above-mentioned~~ said silicone based adhesive agent layer can be stripped from ~~the above-mentioned~~ said undercoat layer after bonding to ~~the above-mentioned~~ said semiconductor wafer.

3. (Currently Amended) The dicing/die bonding sheet according to ~~claims 1 or 2~~ claim 1, wherein ~~the above-mentioned~~ said undercoat layer is a laminate made up of at least two layers.

4. (Currently Amended) The dicing/die bonding sheet according to ~~any of claims 1 through 3~~ claim 1, wherein ~~the above-mentioned~~ said base film has a surface area that is not less than ~~the above-mentioned~~ said semiconductor wafer.

5. (Currently Amended) The dicing/die bonding sheet according to ~~any of claims 1 through 4~~ claim 1, which is coated with a strippable protective layer.

6. (Currently Amended) A method of preparing the dicing/die bonding sheet according to claim 1, which includes the step of forming [[an]] the undercoat layer and [[a]] the silicone based adhesive agent layer on [[a]] the base film.

7. (Currently Amended) The method of preparing a dicing/die bonding sheet according to claim 1, which includes the step of forming [[a]] the silicone based adhesive agent layer and [[an]] the undercoat layer on a stripping layer, the step of applying [[a]] the

base film to [[the]] a surface of the ~~above mentioned~~ undercoat layer, and the step of peeling off the ~~above mentioned~~ stripping layer.

8. (Currently Amended) The method of preparing a dicing/die bonding sheet according to claim 7, which further includes the step of forming a strippable protective layer on the ~~above mentioned~~ silicone based adhesive agent layer after the step of peeling off the ~~above mentioned~~ stripping layer.

9. (Currently Amended) The method of preparing a dicing/die bonding sheet according to claim 5, which includes the step of forming [[a]] the silicone based adhesive agent layer and [[an]] the undercoat layer on [[a]] the strippable protective layer and the step of applying [[a]] the base film to [[the]] a surface of the ~~above mentioned~~ undercoat layer.

Please add the following new claims.

10. (New) The dicing/die bonding sheet according to claim 2, wherein said undercoat layer is a laminate made up of at least two layers.

11. (New) The dicing/die bonding sheet according to claim 2, wherein said base film has a surface area that is not less than said semiconductor wafer.

12. (New) The dicing/die bonding sheet according to claim 3, wherein said base film has a surface area that is not less than said semiconductor wafer.

13. (New) The dicing/die bonding sheet according to claim 10, wherein said base film has a surface area that is not less than said semiconductor wafer.

14. (New) The dicing/die bonding sheet according to claim 2, which is coated with a strippable protective layer.

15. (New) The dicing/die bonding sheet according to claim 3, which is coated with a strippable protective layer.

16. (New) The dicing/die bonding sheet according to claim 4, which is coated with a strippable protective layer.

17. (New) The dicing/die bonding sheet according to claim 10, which is coated with a strippable protective layer.

18. (New) The dicing/die bonding sheet according to claim 11, which is coated with a strippable protective layer.

19. (New) The dicing/die bonding sheet according to claim 12, which is coated with a strippable protective layer.

20. (New) The dicing/die bonding sheet according to claim 13, which is coated with a strippable protective layer.